



DEFENSE LOGISTICS AGENCY
LAND AND MARITIME
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

December 1, 2015

Sue Powers
Hybrid Quality Assurance Engineer
Microsemi Lawrence Corporation
6 Lake Street
Lawrence, MA 01841

Dear Ms. Powers:

Re: Notification of Qualification, Hybrid Microcircuits MIL-PRF-38534, FSC 5962, VQ(VQH-16-029949), CN# 048602, TR 38534-4549-15

Qualification of your processes and materials is granted effective November 30, 2015 under the current issue of the Performance Specification MIL-PRF-38534, Hybrid Microcircuits, FSC 5962. This action is a result of successful qualification in accordance with test report number 38534-4549-15.

The hybrid qualified by this report is identified in Form VQH-42H (MHP8565A, Rev -, dated 8/12/15 - CN# 047945). Your Qualified Manufacturers List (QML) listing will appear as in Enclosure 1 and is subject to the conditions printed in Enclosure 2.

To maintain this listing, you are required to provide a retention report every twelve months. Your standard reporting period is from May 1 through April 30 and your next report is due on May 31, 2016. This report is to include the processes and materials from this qualification. For additional information regarding the retention of qualification report, please review the DLA Land and Maritime-VQH published booklet Certification and Qualification Procedures for MIL-PRF-38534 Hybrid and MCM Microcircuits, located at http://www.landandmaritime.dla.mil/Offices/Sourcing_and_Qualification/resource.aspx.

QML manufacturers shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem affecting QML products. Failure to provide prior notification may be grounds for removal from QML 38534.

To assist us in maintaining the accuracy of your QML, please inform us immediately if your company should discontinue the use of a qualified process or processes.

If you have any questions about this letter, please contact Mr. Hancock at (614) 692-1309.

Sincerely,

JOSEPH GEMPERLINE
Chief
Sourcing and Qualifications Division

Enclosures

CONDITIONS REGARDING QUALIFICATION APPROVAL

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.
6. Continued qualification listing is dependent upon the manufacturer's compliance with the retention of qualification, verification of qualification, to which his products are qualified.

Enclosure 2

Microsemi HRG (CAGE Code: 43611)

6 Lake Street, Lawrence, MA 01841, US

Company Contact: Ms. Sue Powers, Phone: 978-620-2475, Fax: 978-774-0939, E-mail: spowers@microsemi.com

DLA Contact: Mr. Christopher Hancock, Phone: 614-692-1309, Fax: 614-692-6942, E-mail: vqh.ch@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Option 2

Technologies: Point of Load Regulator

Qualification Letters: VQ(VQH-12-025103), VQ(VQH-13-027082), VQ(VQH-15-028926), VQ(VQH-15-029474), VQ(VQH-15-029477), VQ(VQH-15-029572), VQ(VQH-16-029949)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: Purchased Direct Bonded Copper on BeO, 1 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: T3-HPG-FC001

Substrate Attach: Solder

Element Attach: Conductive Epoxy, Solder, Nonconductive Epoxy

Add-on Elements: Chip Capacitors, Unpackaged Die, Chip Resistors, Inductors

Wire Bonding: Aluminum, Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Flatpack, Seam Weld, 3.64 Inch Seal Perimeter, 16 Leads, Gold Lead Finish

Notes:

1/ The QML listing can be expanded provided appropriate qualification testing is performed and passed. Therefore the manufacturer may accept an order for compliant product not covered by his QML listing, but shall not ship the compliant product until the testing has been successfully completed.

2/ Package seal perimeter is listed by largest perimeter successfully tested in inches.

3/ Package lead counts are listed by maximum number of leads covered by qualification.

4/ Caution. Do not use this number for item acquisition. Item acquired to this number may not satisfy the performance requirements of the listed SMD.

5/ Inactive for new design, no longer available from manufacturer.

6/ Class E devices are devices, which meet all of the requirements of one of the other classes (K, H, or G), with some exceptions taken. Therefore any manufacturer qualified to G, H or K is eligible to produce and mark product as compliant to class E.